

ABSTRACT OF THE DISCLOSURE

A polishing apparatus has a top ring configured to hold a semiconductor wafer on a substrate holding surface, and a pusher configured to deliver the semiconductor wafer to the top ring and receive the semiconductor wafer from the top ring. The pusher includes a push stage having a substrate placement surface on which the semiconductor wafer is placed and an air cylinder configured to vertically move the push stage. The pusher also includes a high-pressure fluid port configured to eject a high-pressure fluid toward the semiconductor wafer.